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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **Takayuki USAMI, et al.**

Confirmation No: **1048**

Serial No.: **10/602,646**

Group Art Unit: **1742**

Filed: **June 25, 2003**

Examiner: **IP, SIKYIN**

For: **HIGH-MECHANICAL STRENGTH COPPER ALLOY**

Attorney Docket No.: **020960A**

Customer Number: **38834**

INFORMATION DISCLOSURE STATEMENT
PURSUANT TO 37 CFR 1.97(b)

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

July 16, 2004

Sir:

Applicants direct the attention of the Patent and Trademark Office to the documents listed on the attached Form PTO-1449. One copy of each listed document is attached.


No fee or certification is required in connection with this Information Disclosure Statement, because it is being submitted prior to the issuance of a first official action on the merits or expiration of the three month period following the filing date or the entry of the national stage of the above-captioned application.

The above information is presented so that the Patent and Trademark Office can, in the first instance, determine any materiality thereof to the claimed invention. Applicants respectfully request that the information be expressly considered during the prosecution of this application and that the documents cited in the attached Form PTO-1449 be made of record therein and appear on the first page of any patent to issue therefrom.

The Commissioner is authorized to charge our Deposit Account No. 50-2866 for any fee that is required to effect consideration of this statement.

Respectfully submitted,

WESTERMAN, HATTORI, DANIELS & ADRIAN, LLP

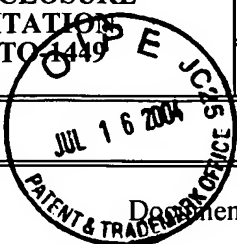

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Attachment: Limited Recognition
PTO-1449 and 33 References

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INFORMATION DISCLOSURE CITATIONS PTO-1449	Atty. Docket No. 020960A	Serial No. 10/602,646
	Applicant(s): Takayuki USAMI, et al.	
	Filing Date: June 25, 2003	Group Art Unit: 1742



U.S. PATENT DOCUMENTS

PATENT & TRADEMARK OFFICE							
Examiner Initial	Document No.	Name	Date	Class	Subclass	Filing Date (If appropriate)	
	AA	4,362,579	Tsuji	12/07/1982	148	11.5	12/24/1980
	AB	4,877,577	Futatsuka, et al	10/31/1989	420	473	10/12/1988
	AC	5,028,391	Ingerson	07/02/1991	420	488	12/26/1989
	AD	5,334,346	Kim, et al	08/02/1994	420	4.85	02/18/1993
	AE	5,463,247	Futatsuka, et al	10/31/1995	257	666	02/15/1994
	AF	5,833,920	Nakanishi et al.	11/10/1998	420	477	02/19/1997
	AG	4,594,221	Caron et al.	06/10/1986	420	485	04/26/1985
	AH	4,728,372	Caron et al.	03/01/1988	148	2	12/30/1985

FOREIGN PATENT DOCUMENTS

FOREIGN PATENT DOCUMENTS					
Examiner Initial		Document No.	Date	Country	Translation (Yes or No)
	AI	JP 11-256256	09/21/1999	Japan	Yes (Abstract only)
	AJ	JP 01-180932	07/18/1989	Japan	Yes (Abstract only)
	AK	JP 06-100983	04/12/1994	Japan	Yes (Abstract only)
	AL	JP 61-127842	06/16/1986	Japan	Yes (Abstract only)
	AM	JP 63-130739	06/02/1988	Japan	Yes (Abstract only)
	AN	JP 59-193233	11/01/1984	Japan	Yes (Abstract only)
	AO	JP 07-54079	02/28/1995	Japan	Yes (Abstract only)
	AP	JP 10-330867	12/15/1998	Japan	Yes (Abstract only)
	AQ	JP 02-170937	07/02/1990	Japan	Yes (Abstract only)
	AR	JP 02-118037	05/02/1990	Japan	Yes (Abstract only)
	AS	JP 07-90520	04/04/1995	Japan	Yes
	AT	JP 11-222641	08/17/1999	Japan	Yes
	AU	JP 05-59468	03/09/1993	Japan	Yes
	AV	JP 11-43731	02/16/1999	Japan	Yes
	AW	JP 06-41660	02/15/1994	Japan	Yes
	AX	TW 448235	08/01/2001	Taiwan	Yes (Abstract only)
	AY	EP 0 440 548	08/07/1991	Europe	N/A



Serial No. 10/602,646

OTHER DOCUMENTS

	<div>U.S. PATENT & TRADEMARK OFFICE</div> <div>AZ</div> <div>BA</div> <div>BB</div> <div>BC</div> <div>BD</div> <div>BE</div> <div>BF</div> <div>BG</div>	<div>Taiwanese Office Action dated November 13, 2002, for a corresponding Taiwan application of U.S. Application S.N.10/005,880, w/English translation</div> <div>Journal of the Japan Copper and Brass Research Association, 2001, Vol. 40, w/concise explanation thereof</div> <div>Furukawa Electric Review, No. 107, January 2001, w/concise explanation thereof</div> <div>Synopses of the 38th Symposium of Copper and Brass Technical Research Association, published on September 22, 1998, w/English translation</div> <div>Synopses of the 40th Symposium of Copper and Brass Technical Research Association, published on September 20, 2000, w/English translation</div> <div>33rd Annual IICIT, 2000 Conference Proceeding of October 23, 2000</div> <div>U.S. Application No. 09/966,389 (Publication No. US 2002/0119071)</div> <div>U.S. Application No. 10/005,880 (Publication No. US 2002/0127133)</div>
Examiner	Date Considered	